Universal Instruments
AREA Consortium Meeting – April 2026

The April 2026 meeting of the AREA Consortium will be an online broadcast and in-person meeting held in the Engineering Sciences Building (ES2008) on Binghamton University research campus. Web meeting links will be provided to consortium members and partners under separate copy.

Wednesday, April 1, 2026

EDT

08:30	Welcome
08:45 Jeff Kurish	Cross-Sectional imaging of Soft Indium Solder Thermal Interface Materials with Thermal Cycling
09:15 Mike Meilunas	Electromigration Update: SAC305 and Cyclomax
10:15	***Break***
10:45 Jeff Kurish	Process Investigation of Vacuum Reflow Within Multiple Reflow Steps.
11:15 Mike Meilunas	“High Reliability” Solder Paste Performance in Accelerated Thermal Cycling
11:45 Dave Vicari	The Future of UIC APL Process and Reliability Research
12:05	***Lunch***

On-going APL Research Collaborations

13:15 Jeff Kennedy	Large Body BGA Assembly
13:40 Mike Meilunas	Tin Whisker Measurement Collaboration
14:00	Wrap-Up Discussion
14:15	***Adjourn***

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